



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

re PATENT APPLICATION of

Takashi Ohsumi

Attorney Docket No. IIZ.003D2C

Serial No.: 10/689,936

Examiner: F. Toledo

Filed: October 22, 2003

Art Unit No.: 2823

For: A METHOD FOR FABRICATING A SEMICONDUCTOR APPARATUS
INCLUDING A SEALING MEMBER WITH REDUCED THERMAL STRESS

LETTER OF RELATED APPLICATION

U.S. Patent and Trademark and Trademark Office
Customer Window, Mail Stop
Randolph Building
401 Dulany Street
Alexandria, VA 22314

Date: April 25, 2005

Sir:

The Examiner is hereby advised of co-pending U.S. Application Serial No. 10/957,620. The subject matter contained in this co-pending U.S. Application Serial No. 10/957,620 is related to the present application and thus may be material to the prosecution of this instant application.

This application is not to be construed as prior art. By bringing this application to the attention of the Examiner, Applicant does NOT waive the confidentiality provisions of 35 U.S.C. 122.

Respectfully submitted,

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